

SOT1534-4

LFBGA289, plastic, low profile fine-pitch ball grid array; 289 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.37 mm body

8 October 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA289
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-09-2019
Manufacturer package code	98ASA01216D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	13.85	14	14.15	mm
package width	13.85	14	14.15	mm
package height	-	1.37	1.52	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	289	-	



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2 Package outline

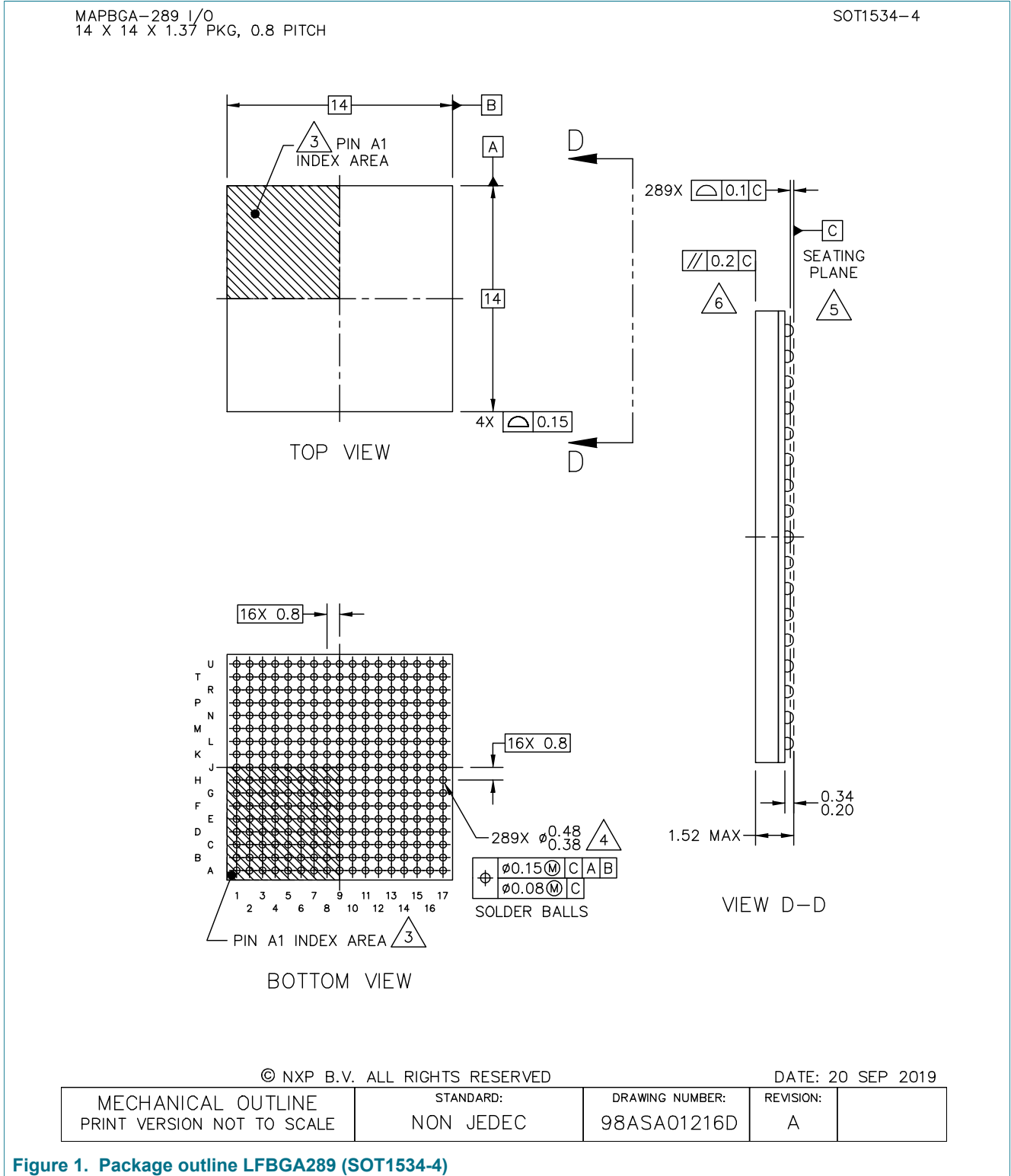
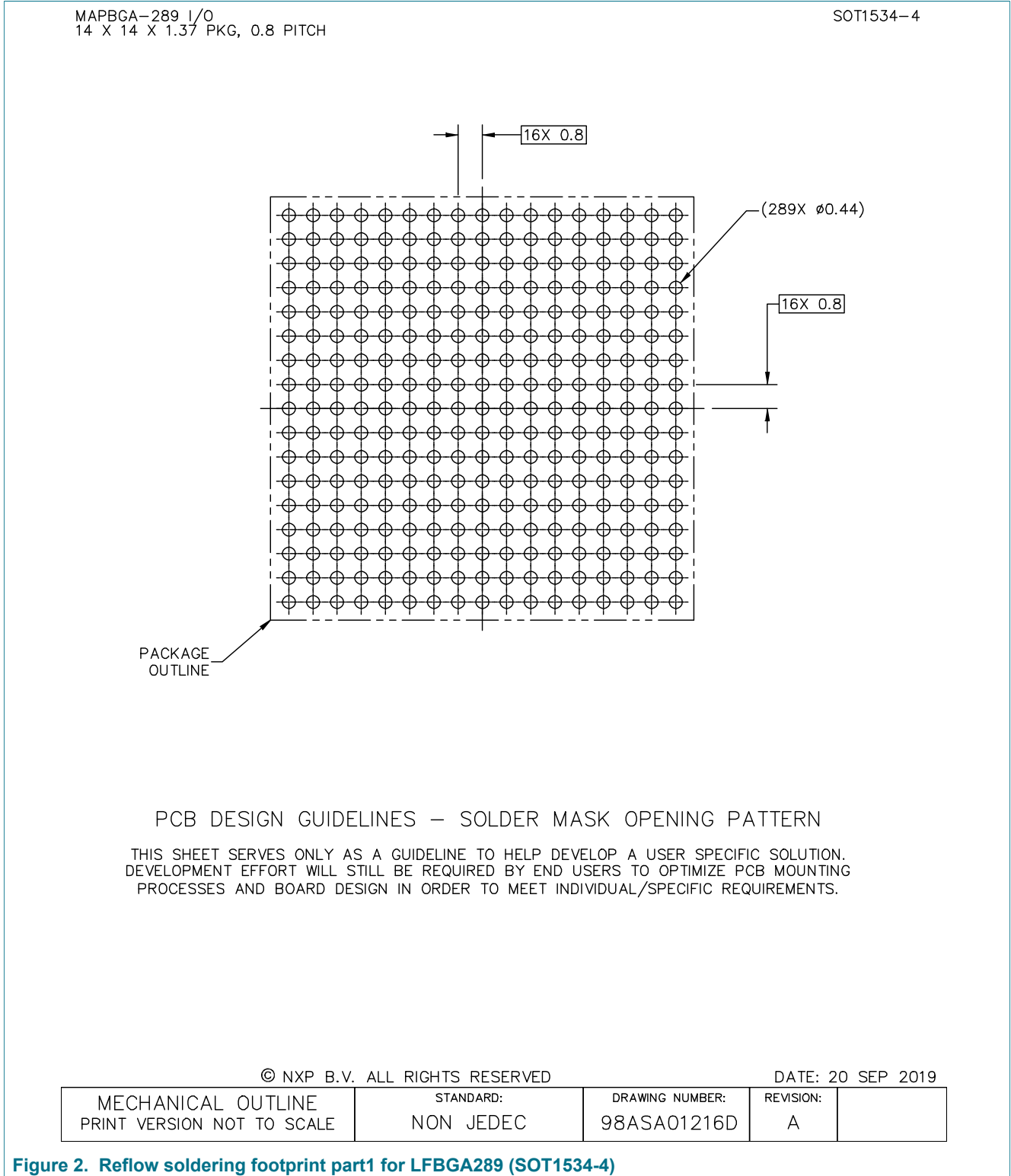


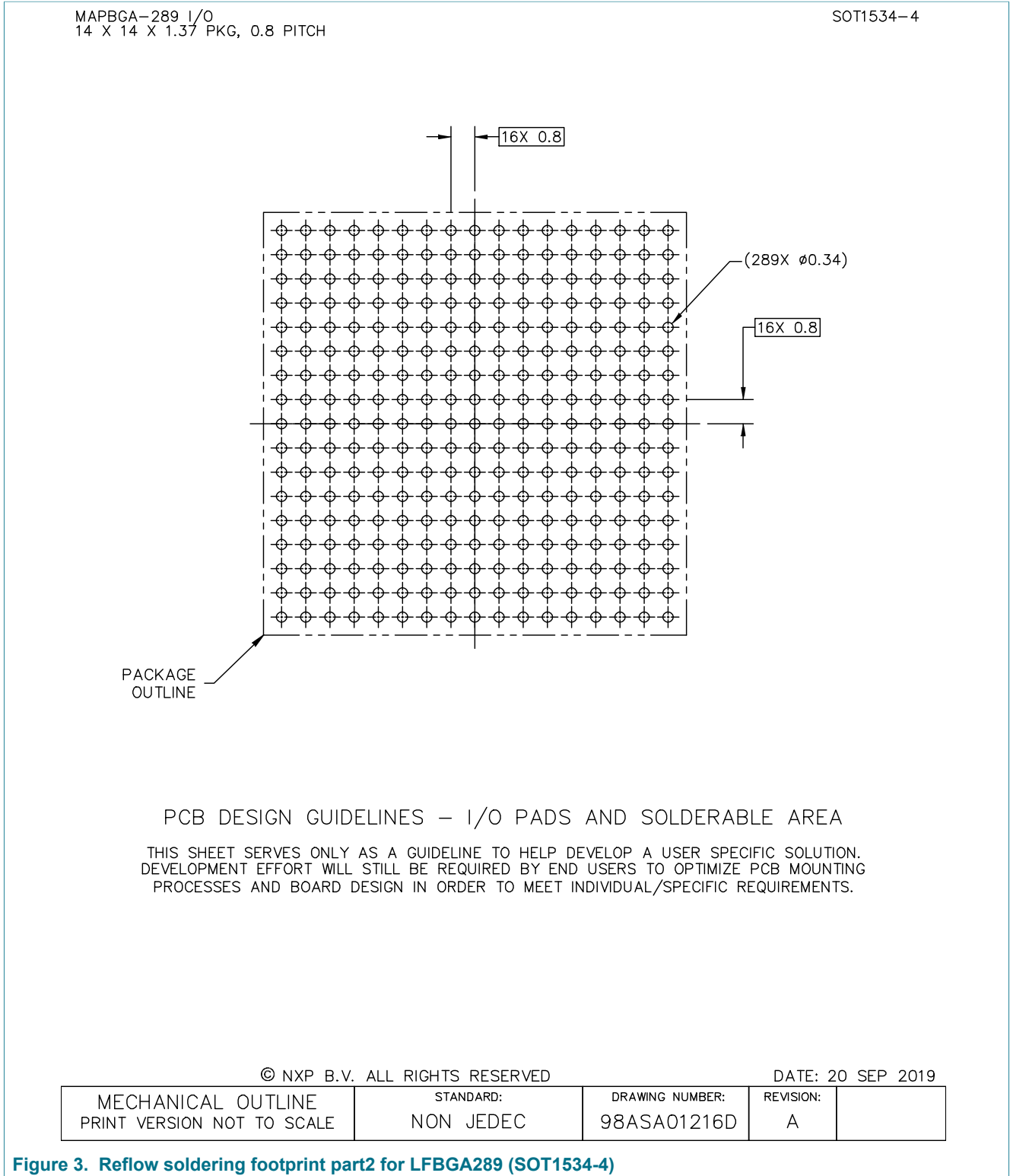
Figure 1. Package outline LFBGA289 (SOT1534-4)

LFBGA289, plastic, low profile fine-pitch ball grid array; 289 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.37 mm body

3 Soldering



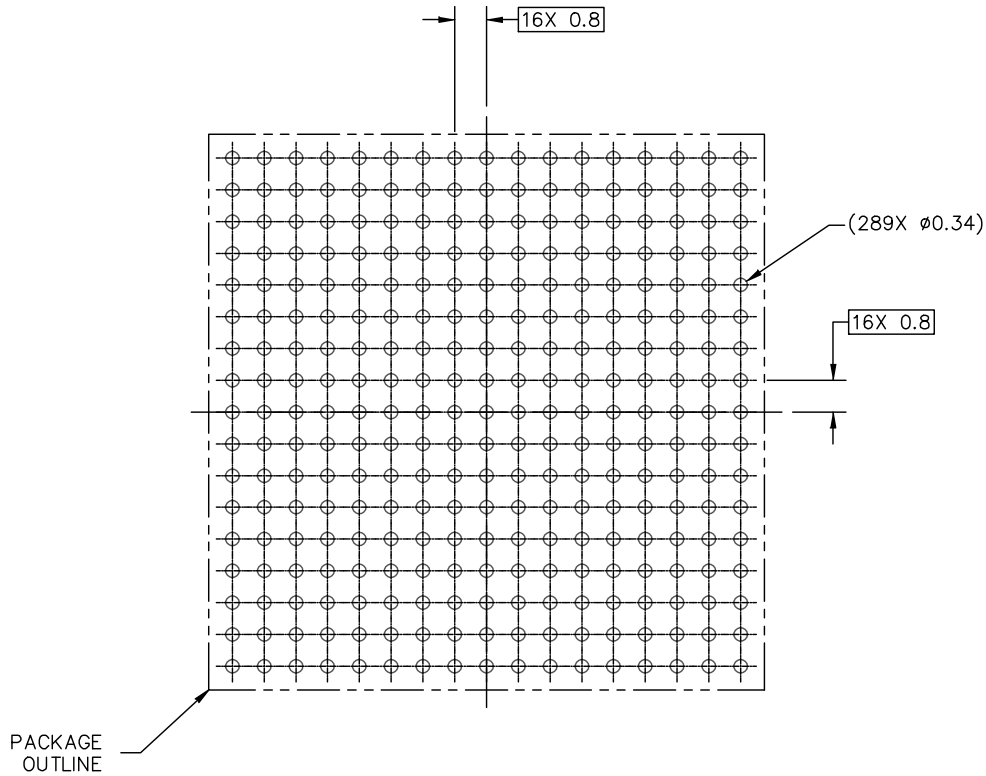
LFBGA289, plastic, low profile fine-pitch ball grid array; 289 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.37 mm body



LFBGA289, plastic, low profile fine-pitch ball grid array; 289 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.37 mm body

MAPBGA-289 I/O
14 X 14 X 1.37 PKG, 0.8 PITCH

SOT1534-4



RECOMMENDED STENCIL THICKNESS 0.125
PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 20 SEP 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01216D	REVISION: A	
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Figure 4. Reflow soldering footprint part3 for LFBGA289 (SOT1534-4)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note LFBGA289 (SOT1534-4)

4 Legal information

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